FAIRCHILD SEMICONDUCTOR™

October 1994
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74F1071
18-Bit Undershoot/Overshoot Clamp and ESD Protection Device

General Description

The 74F1071 is an 18-bit undershoot/overshoot clamp which is designed to limit bus voltages and also to protect more sensitive devices from electrical overstress due to electrostatic discharge (ESD). The inputs of the device aggressively clamp voltage excursions nominally at 0.5V below and 7V above ground.

Features

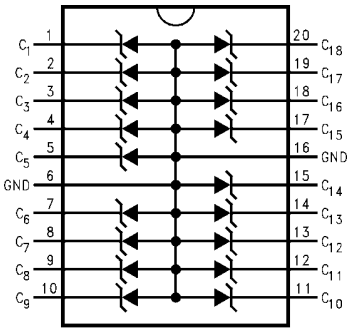
- 18-bit array structure in 20-pin package
- FAST® Bipolar voltage clamping action
- Dual center pin grounds for min inductance
- Robust design for ESD protection
- Low input capacitance
- Optimum voltage clamping for 5V CMOS/TTL applications

Ordering Code:

Order Number	Package Number	Package Description
74F1071SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F1071MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74F1071MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram



Note: Simplified Component Representation

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Absolute Maximum Ratings(Note 1)

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−65°C to +125°C
Junction Temperature under Bias	−65°C to +150°C
Input Voltage (Note 2)	−0.5V to +6V
Input Current (Note 2)	−200 mA to +50 mA
ESD (Note 3)	
Human Body Model	
(MIL-STD-883D method 3015.7)	±10 kV
IEC 801-2	±6 kV
Machine Model (EIAJIC-121-1981)	±2 kV
DC Latchup Source Current	
(JEDEC Method 17)	±500 mA
Package Power Dissipation @+70°C	
SOIC Package	800 mW

Recommended Operating Conditions

Free Air Ambient Temperature	0°C to +70°C
Reverse Bias Voltage	0V to 5.25 V_{DC}
Thermal Resistance (θ_{JA} in Free Air)	
SOIC Package	100°C/W
SSOP Package	110°C/W

Note 1: Absolute maximum ratings are DC values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Voltage ratings may be exceeded if current ratings and junction temperature and power consumption ratings are not exceeded.

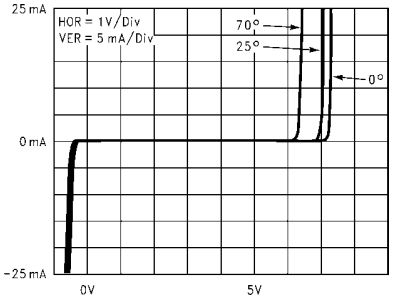
Note 3: ESD Rating for Direct contact discharge using ESD Simulation Tester. Higher rating may be realized in the actual application.

DC Electrical Characteristics

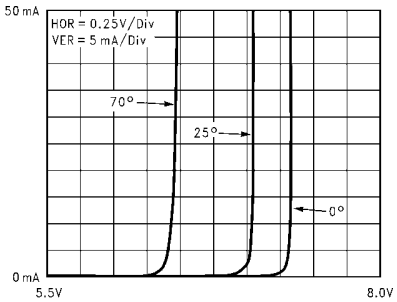
Symbol	Parameter	T_A = +25°C			T_A = 0°C to +70°C		Units	Conditions
		Min	Typ	Max	Min	Max		
I_{IH}	Input HIGH Current		1.5	10		50	µA	V_{IN} = 5.25V; Untested Input @ GND
			3	20		100		V_{IN} = 5.5V; Untested Input @ GND
V_Z	Reverse Voltage	6.6	6.9	7.2	5.9	7.7	V	I_Z = 1 mA; Untested Inputs @ GND
			7.1	7.5		8.0		I_Z = 50 mA; Untested Inputs @ GND
V_F	Forward Voltage	−0.3	−0.6	−0.9	−0.3	−0.9	V	I_F = −18 mA; Untested Inputs @ 5V
		−0.5	−1.1	−1.5	−0.5	−1.5		I_F = −200 mA; Untested Inputs @ 5V
I_{CT}	Adjacent Input Crosstalk			3			%	
C_{IN}	Input Capacitance		25				pF	V_{BIAS} = 0 V_{DC}
	(small signal @ 1 MHz)		13					V_{BIAS} = 5 V_{DC}

DC Electrical Characteristics

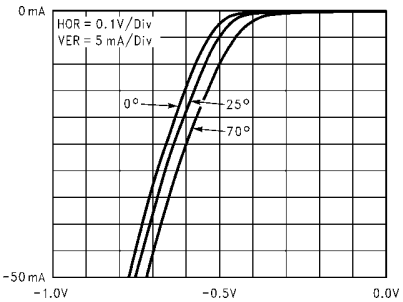
Typical Forward and Reverse V/I Characteristics

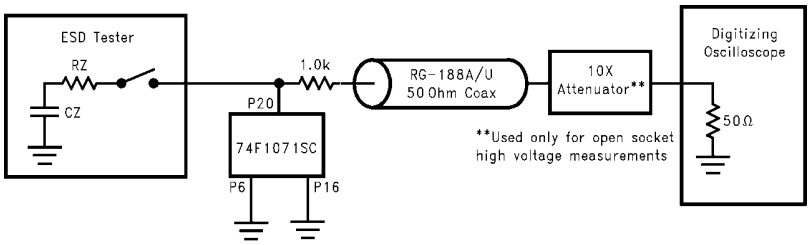


Typical Reverse Conduction Characteristics



Typical Forward Conduction Characteristics



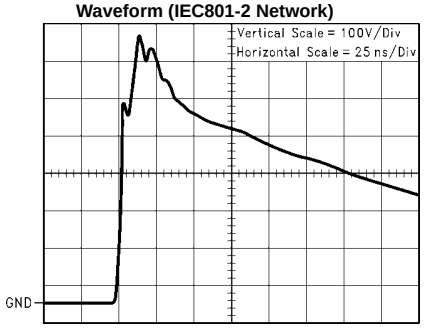


ESD Network	CZ	RZ
Human Body Model	100 pF	1500Ω
IEC 801-2	150 pF	330Ω

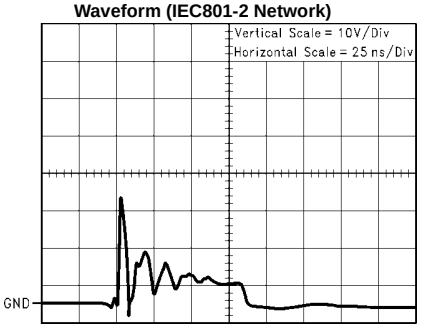
Simulated ESD Voltage Clamping Test Circuit

DC Electrical Characteristics (Continued)

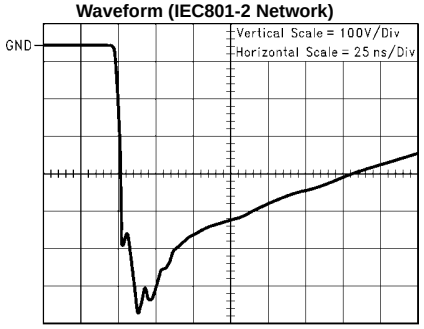
Unclamped + 1 KV ESD Voltage Waveform (IEC801-2 Network)



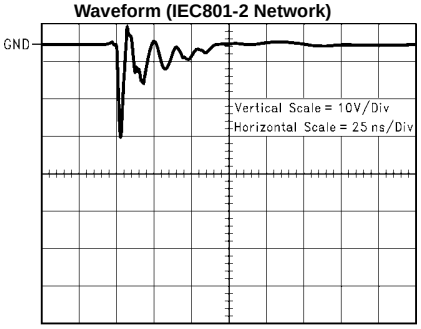
Clamped + 1 KV ESD Voltage Waveform (IEC801-2 Network)



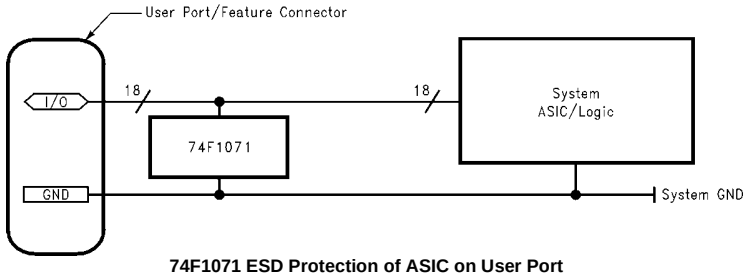
Unclamped - 1 KV ESD Voltage Waveform (IEC801-2 Network)



Clamped - 1 KV ESD Voltage Waveform (IEC801-2 Network)

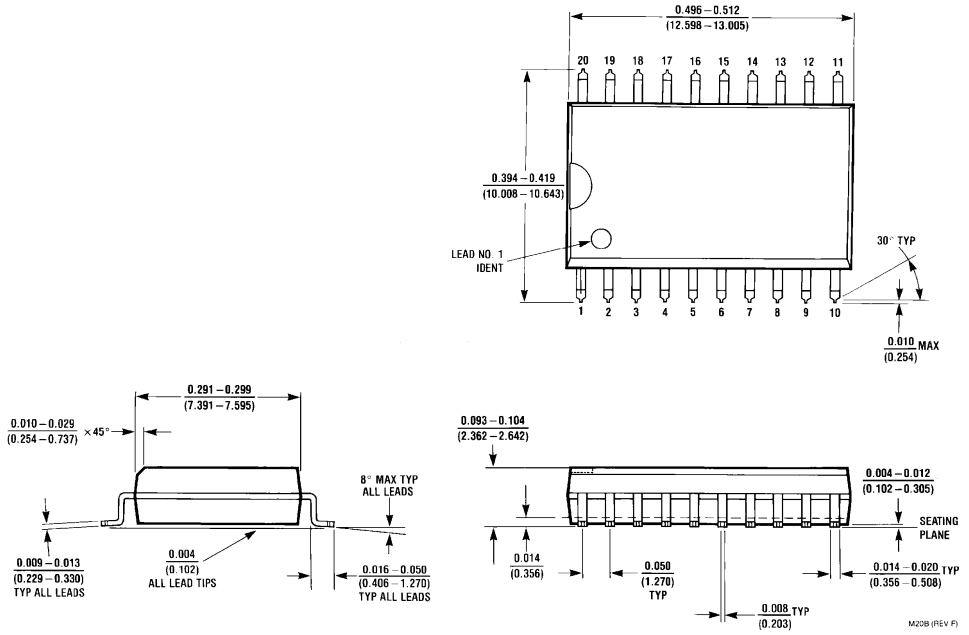


Typical Application

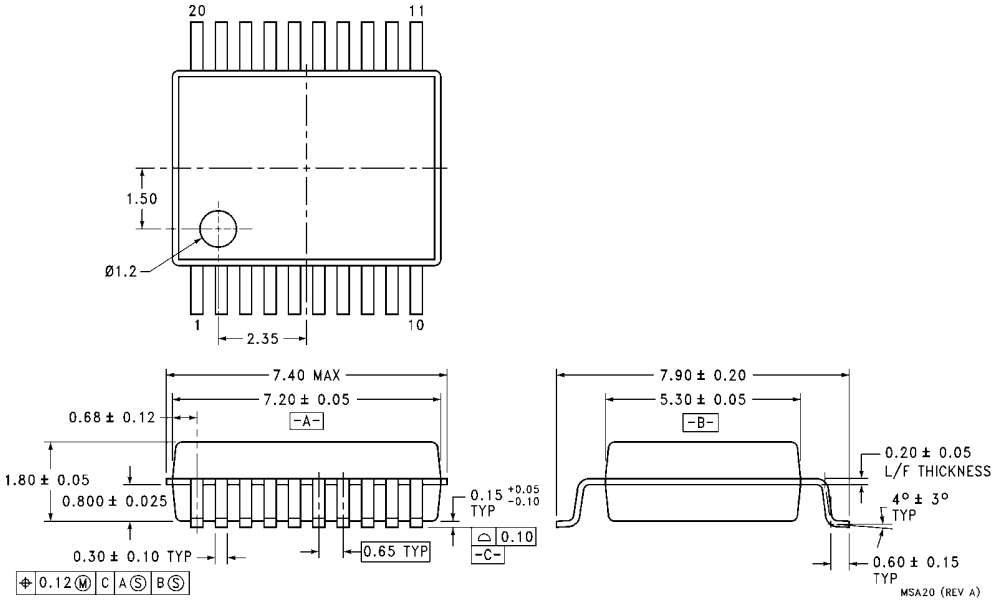


74F1071 ESD Protection of ASIC on User Port

Physical Dimensions inches (millimeters) unless otherwise noted

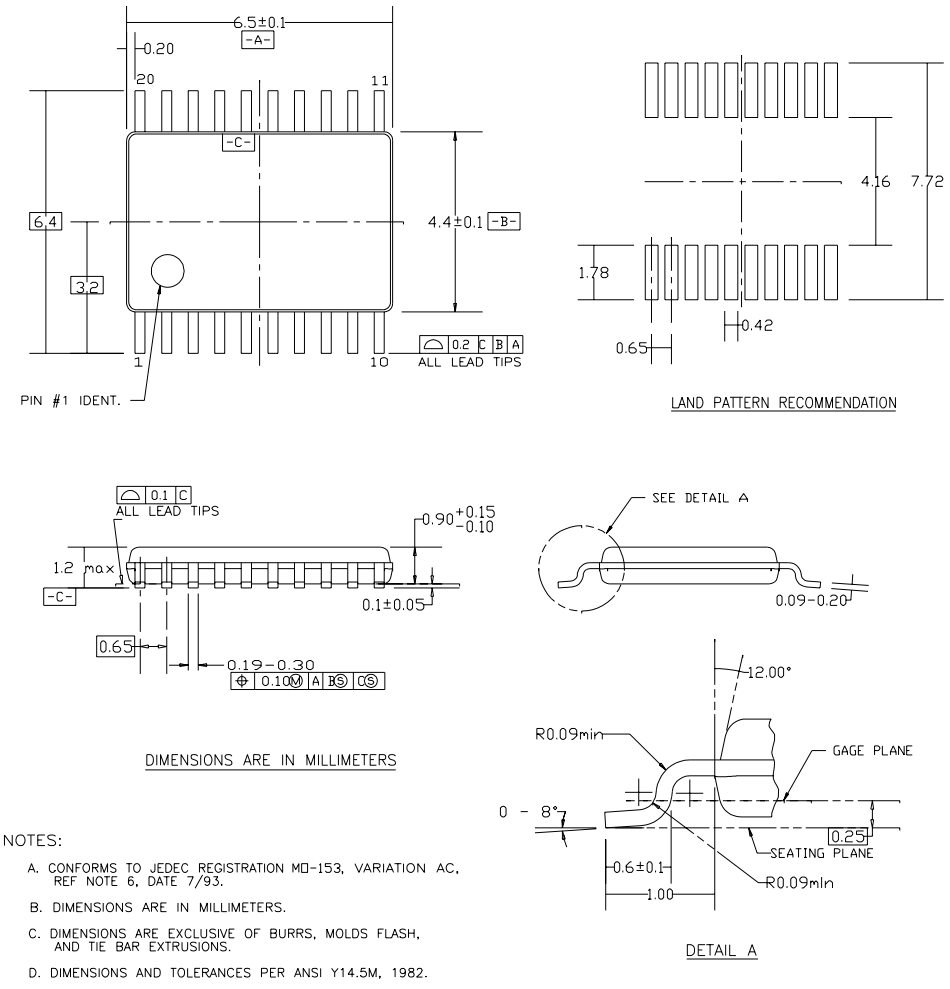


20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
Package Number M20B



20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
Package Number MSA20

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.

D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC20

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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